Wire Wound Chip Inductor
-YWIF1608 Series

■ Features

- Minature size,suitable for SMT.
- Using terminal electrode structure to restrain the parasitic component effect quite caused by lead.
- Execellent in solderability and heat resistance.
- Best frequency special property and intense ability to resist interference.
- Operating temperature:-40℃ ~ +85℃.

■ Applications

- Protable communication equipment and PDA,high speed electronic device.
- Used for radiation high speed noise suppression.

■ Product Identification

YWIF (1) □□□□ (2) - □□□ (3) - □ (4)

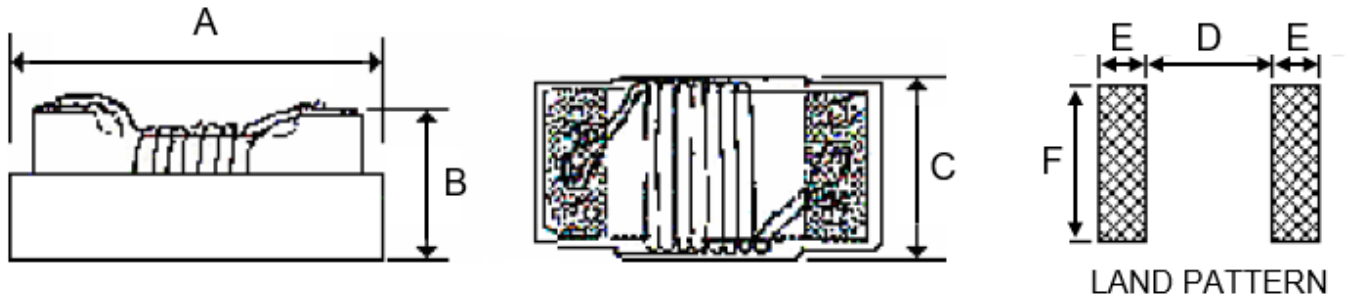
(1)： Type

(2)： Dimensions

(3)： Inductance value

(4)： Inductance Tolerance: M=±20%,K=±10%,J=±5%

■ Shapes and Dimensions (Unit：mm)



TYPE	A Max.	B Max.	C Max.	D Typ.	E Typ.	F Typ.
YWIF1608	1.80	1.10	1.25	0.64	0.64	1.02

■ YWIF1608 Series

Part Number	L (uH)	Freq. (MHz)	Q Min.	SRF Typ. (MHz)	Rdc Max. (Ω)	Irms Typ. (mA)
YWIF1608-R12K	0.12±10%	7.9	12	1000	0.15	1000
YWIF1608-R15K	0.15±10%	7.9	12	950	0.15	1000
YWIF1608-R18K	0.18±10%	7.9	12	950	0.20	1000
YWIF1608-R22K	0.22±10%	7.9	12	775	0.30	700
YWIF1608-R27K	0.27±10%	7.9	12	775	0.30	700
YWIF1608-R33K	0.33±10%	7.9	12	725	0.32	600
YWIF1608-R39K	0.39±10%	7.9	12	620	0.51	500
YWIF1608-R47K	0.47±10%	7.9	12	540	0.43	570
YWIF1608-R56K	0.56±10%	7.9	12	600	0.65	400
YWIF1608-R68K	0.68±10%	7.9	12	500	1.00	380
YWIF1608-R82K	0.82±10%	7.9	12	500	1.30	350
YWIF1608-1R0K	1.0±10%	7.9	12	400	0.81	330
YWIF1608-1R2K	1.2±10%	7.9	12	380	1.70	320
YWIF1608-1R5K	1.5±10%	7.9	12	300	1.30	310
YWIF1608-1R8K	1.8±10%	7.9	12	180	2.20	300
YWIF1608-2R2K	2.2±10%	7.9	12	180	2.30	280
YWIF1608-2R7K	2.7±10%	7.9	12	150	2.60	250
YWIF1608-3R3K	3.3±10%	7.9	12	150	2.90	230
YWIF1608-3R9K	3.9±10%	7.9	12	100	2.00	200
YWIF1608-4R7K	4.7±10%	7.9	12	100	4.00	200
YWIF1608-5R6K	5.6±10%	7.9	12	32	2.60	240
YWIF1608-6R8K	6.8±10%	7.9	12	31	3.90	200
YWIF1608-8R2K	8.2±10%	7.9	12	26	4.20	190
YWIF1608-100K	10±10%	2.5	12	25	4.80	180
YWIF1608-150K	15±10%	2.5	10	23	8.50	170
YWIF1608-220K	22±10%	2.5	10	10	12.00	100

※ Rating DC current:temperature rise(ΔT) is 40 ℃ approximately at Irms.

※ Saturation DC current:Inductance drop approximately 30% of L0 at Isat.

※ Storage temp.:-10℃ ~ + 40℃ R.H.:65% Max.

※ Moisture sensitivity level(MSL)2(1 year floor life at<30℃/65% relative humidity)

■ Soldering Conditions

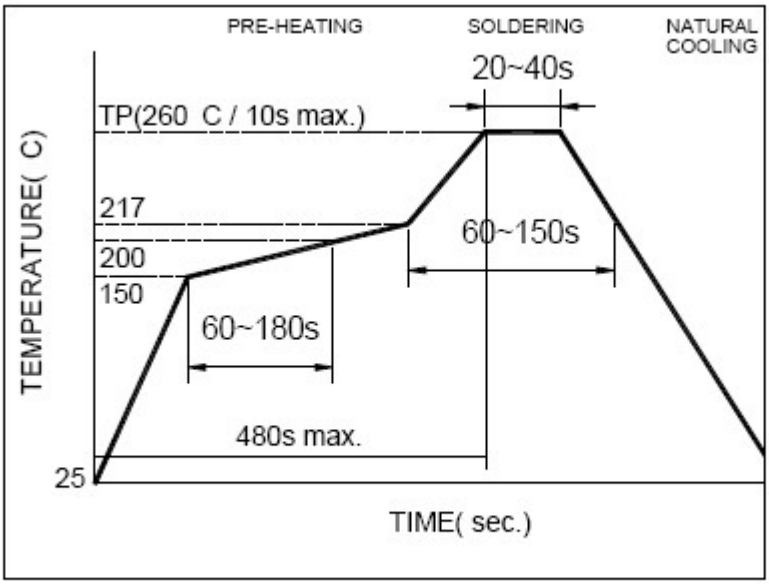


Figure 1. Re-flow Soldering (Lead Free)

Note:
- Preheat circuit and products to 150℃
- 260℃ tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

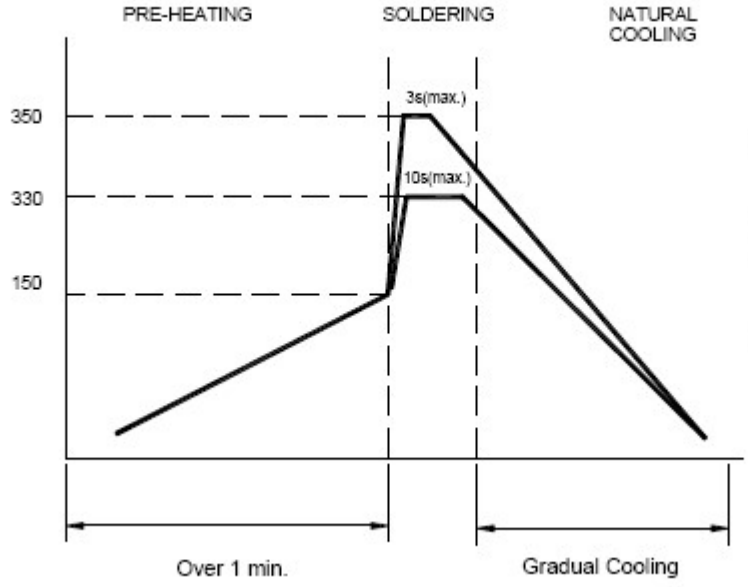
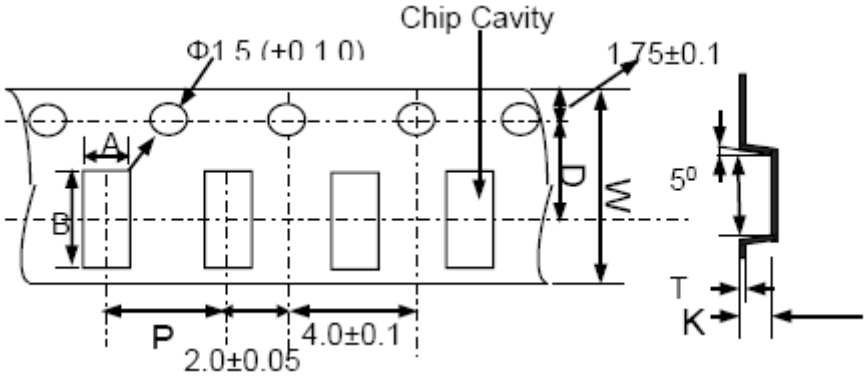


Figure 2. Hand Soldering

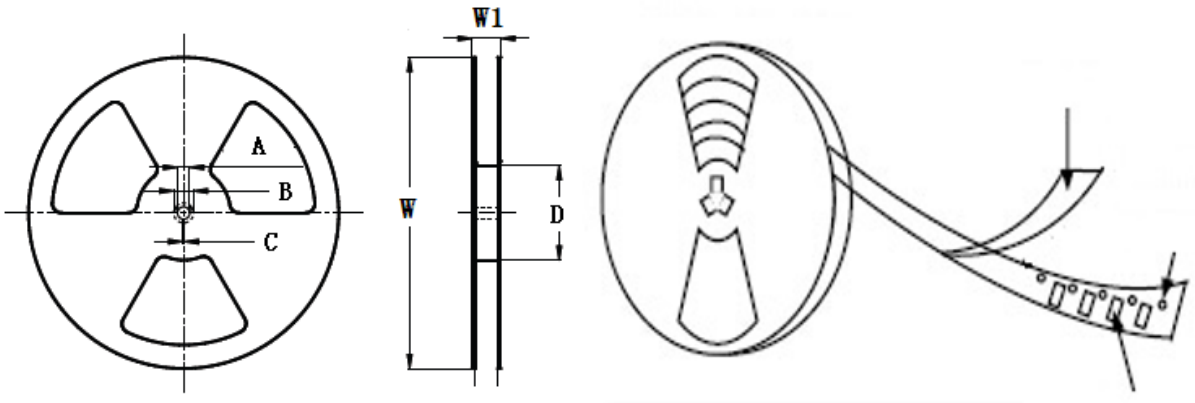
Note:
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

■ Taping Dimensions(Unit:mm)



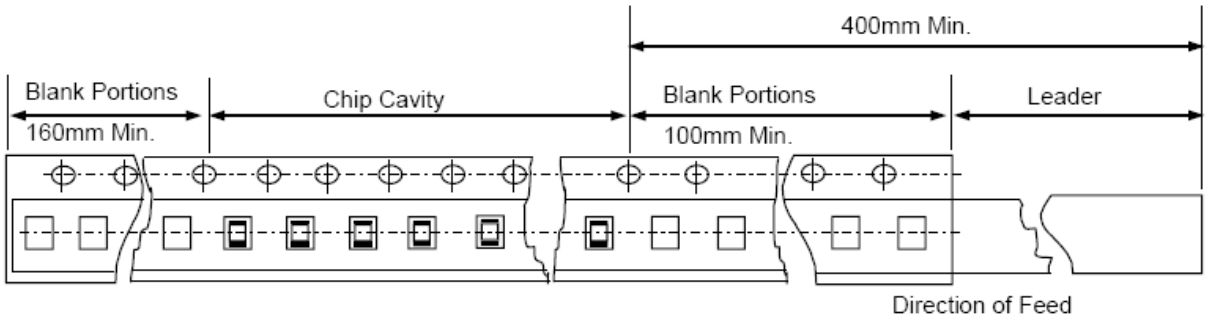
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YWIF1608	8.00	1.50	2.30	3.50	4.00	1.10	0.30	4000

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	A	B	C	D
YWIF1608	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

■ Leader and Blank portion



1．Missing chips number within 0.1% of the number per reel or 1pcs, whichever is greater, and are not continuous.

2．The top tape and bottom tape shall not protrude beyond the edges of the tape and shall not cover sprocket hole.

3．Cumulative tolerance of sprocket holes, 10 pitches: ±0.3mm.

4．Peeling off force: 10gf to 100gf in the direction show below for 8mm carrier tapes and 10gf to 130gf for 12mm to 56mm wide carrier tapes.

